



Click [here](#) for the 3D model.

Dimensions

Chip Size	0402
L	1.02mm +0.15/-0.1mm (0.04 in +0.006/-0.004 in)
W	0.51mm +0.13/-0.1mm (0.02 in +0.005/-0.004 in)
T	0.64mm MAX (0.025 in MAX)
B	0.1mm MIN (0.004 in MIN)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	368

General Information

Series	SMD MIL X7R PRF32535
Style	SMD Chip
Description	SMD, Military, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535
AEC-Q200	No
Component Weight	1600 ug

Specifications

Capacitance	0.018 uF
Capacitance Tolerance	10%
Voltage DC	16 VDC
Dielectric Withstanding Voltage	40 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Dissipation Factor	3.5% 1 MHz 25C
Aging Rate	3% Loss/Decade Hour
Insulation Resistance	27.78 GOhm

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)